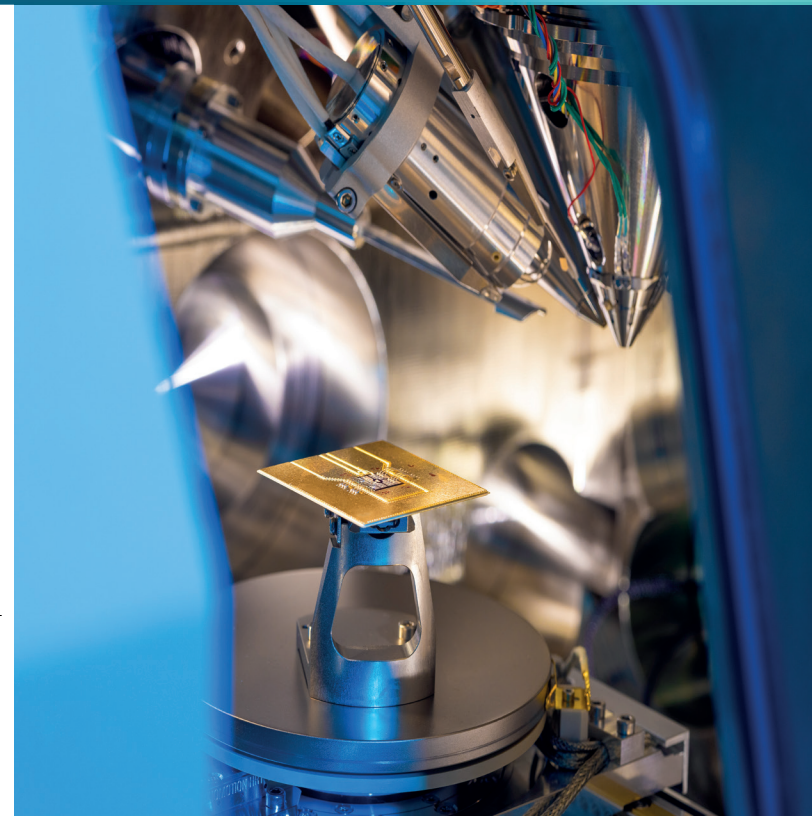




**Fraunhofer**
IMWS

Fraunhofer Institute for Microstructure of Materials and Systems IMWS

Innovation in Failure Analysis and Material Diagnostics of Electronics Components

13th CAM-Workshop
19 - 20. May 2026

Social Programm

Tuesday, 20.05.2025 | 18:10 - 19:00 | Exhibition Area



Drinks Reception

Be sure not to miss our drinks reception in the exhibition area – starting straight after the workshop. Refreshments and finger foods will be provided for all delegates attending the conference.

Tuesday, 20.05.2025 | 19:00 - 22:00 |

Gardens at Leibniz IAMO



Networking Dinner

Our live band will be performing popular classics while you enjoy a meal in the beautiful gardens of Leibniz IAMO. This gives you a chance to continue your discussions about FA trends, developments and products within a relaxed and informal atmosphere. All participants are invited to join us!

Contact

Fraunhofer IMWS
Walter-Huelse-Str. 1
06120 Halle

www.imws.fraunhofer.de

20 - 21. May 2025

Innovation in Failure Analysis and Material Diagnostics of Electronics Components

www.cam-workshop.de

**WIFI**

network name: IAMO
password: Turns Schuh1A



Tuesday, 20.05.2025

SESSION A: Welcome and Keynotes

- 09:00
- Welcome
Frank Altmann | Fraunhofer IMWS (DE)
- 09:40
- Keynote: The APECS Pilot Line: European Chiplet Innovation
Albert Heuberger | Fraunhofer IIS (DE)
- 10:00
- Keynote: Reliability challenges of Silicon Photonic devices and its related Failure Analysis challenges
Kristof Croes | IMEC (BE)
- 10:40
- Keynote: MEMS: Smart sensors for a sustainable AI
Mikel Azpeitia Urquia | ST Microelectronics (IT)

SESSION B: MEMS & Sensors

- 11:20
- Micromechanics without walking the plank - MEMS characterization at Infineon Regensburg
Holger Pfaff | Infineon Technologies (DE)
- 11:40
- Understanding Wafer Bonded MEMS by (Failure) Analysis
Roy Knechtel | University of Applied Sciences Schmalkalden (DE)
- 12:00
- Pinpointing Leakage Defects in TSVs: A Refined Failure Analysis Approach
Georg Spanring | AMS-Osram AG (AT)
- 12:20
- Implantation related crystallographic defects in pressure sensors
Bernd Hähnlein | CIs Forschungsinstitut für Mikrosensorik (DE)

12:40 Lunch Break / Exhibition

SESSION C: Emerging Fault Isolation Techniques

- 14:00
- Exploring the Capabilities and Applications of E-beam probing for Failure Analysis
Neel Leslie | Thermo Fisher Scientific (US)
- 14:20
- Innovative Approaches to Ultra Thinning Silicon to Enabling New Insights in IC Failure Analysis
Michael Di Battista | Varioscale Inc. (US)

- 14:40
- Challenges for Nanoprobng of 22nm FDSOI devices
Pascal Limbecker | GlobalFoundries Dresden Module One LLC & Co. KG (DE)(DE)
- 15:00
- Precise 3D Defect Localization in quantitative Lock-in Thermography by analyzing the spatial phase distribution
Sebastian Brand | Fraunhofer IMWS (DE)
- 15:20
- Application to a failure analysis of Visible ThermoDynamic ® Imaging
Shimpei Tominaga | Hamamatsu (JP)
- 15:40
- RF-LIT background and use cases
Marc van Veenhuizen | NXP (NL)
- 16:00
- Coffee Break / Exhibition

SESSION D: Vendor FA Road Map

- 16:40
- Hamamatsu OFI roadmap
Thomas Reichart | Hamamatsu Photonics Deutschland GmbH (DE)
- 16:50
- HD Lock-in Thermography for Failure Analysis in Electronics
Steffen Sturm | InfraTec GmbH Infrarotsensorik und Messtechnik (DE)
- 17:00
- Minimizing Electron Beam Exposure to the Sample During Nanoprobng
Marc Heinemann | SmarAct Metrology GmbH & Co. KG (DE)
- 17:10
- Mechanical Preparation of a SiC Power module - A Case Study
Chris Richardson | Allied High Tech Products (US)
- 17:20
- Efficiency Meets Precision: Advanced Laser Solutions for Sample Preparation
Oytun Tasgit | 3D-Micromac AG (DE)
- 17:30
- Thermo Fisher Scientific FA Road Map
Ondrej Baco | Thermo Fisher Scientific Brno s.r.o (CZ)
- 17:40
- Automation toolkit for electron microscopy workflows
Thomas Rodgers | Carl Zeiss Microscopy GmbH (DE)



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- 17:50
- TESCAN Failure Analysis Roadmap Status Update
Lukas Hladik | Tescan Group, a.s. (CZ)
- 18:00
- Fault Isolation in the Chiplet Packaging Era
Martin Igarashi | TeraView LTD. (US)
- 18:10
- Drinks Reception
- 19:00
- Social Program: Networking Dinner

Abstracts



All abstract can be found on the CAM-Workshop Website:

<https://cam-workshop.de/abstracts-25/>

Or by simply scanning the adjacent QR-Code.

Wednesday, 21.05.2025

SESSION E: Tutorial

- 08:00
- Deep level effects, failure modes and mechanisms of GaN HEMTs; current understanding and open questions
Enrico Zanoni | University OF Padua (IT)
- 09:00
- Coffee Break / Exhibition

SESSION F: GaN electronics

- 09:40
- Keynote: Gallium Nitride Power Devices and Systems: Benefits and Industrial Realization
Thomas Detzel | Infineon Technologies Austria AG (AT)
- 10:20
- Cascode GaN devices for high power application
Victor Sizovl Nexperia (NL)
- 10:40
- A direct correlation of dislocation characterization in GaN by scanning electron and scanning transmission electron microscopes
Aidan Taylor | Infineon Villach (AT)

- 11:00
- Defect characterization in compound semiconductors using cathodoluminescence
Marc Fouchier | IAttolight (CH)
- 11:20
- Novel approach of combined planar and cross-sectional defect analysis of stressed normally-on HEMT devices with leaky Schottky gates
Michél Simon-Najasek | Fraunhofer IMWS (DE)
- 11:40
- Reliability characterization challenges for wide bandgap power electronics
Daniel Wetzel | X-FAB (DE)
- 12:00
- Towards affordable GaN power modules – advanced interconnect materials & solutions
Sebastian Fritzsche | Heraeus Electronics GmbH & Co. KG (DE)
- 12:20
- Lunch Break / Exhibition

SESSION G: AI Applications and FA Workflows

- 13:40
- Keynote: Towards a Sustainable AI Lifecycle in FA Labs
Konstantin Schekotihin | University Klagenfurt (AT)
- 14:20
- Automated Infrared Microscopy Workflow – Image Acquisition and AI Anomaly Detection
Sebastian Stolwijk | BOSCH (DE)
- 14:40
- Leveraging Machine Signals for Device-Level Quality Detection and Automatic Root Cause Analysis in Semiconductor Wire Bonding
Kenneth J. Braakman | NXP (NL)
- 15:00
- Speeding up FA workflows by AI – first results from the FA2IR project
Bernhard Fichtl | Carl Zeiss Microscopy GmbH (DE)
- 15:20
- Digital workflows and ML techniques to optimize failure analysis in microelectronics
Amit-Kumar Choudhary | Matworks GmbH (DE)
- 15:40
- Simplifying ML-Based Signal Analysis in FA by Removing Equipment Related Transfer Properties
Lorenz Heinemann | Fraunhofer IMWS (DE)
- 16:00
- Enhancing Semiconductor Nanoprobng procedures with AI-Driven Tip Detection
David Stefan Kleindiek | Kleindiek Nanotechnik (DE)
- 16:20
- Failure Analysis Ontology for structuring FA knowledge and meta data in a machine and human readable format
Christoph Maier | Infineon Technologies AG (DE)